Last Gasp Hold Up Energy Storage Solution

Project Title:

Designed for: Public Release

Assembly Variant: Variant name not interpreted

http://www.ti.com

Contact: http://www.ti.com/support

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Drawn By:

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Not in version control

SVN Rev:

TIDA-00304

Number:

Rev:

E1

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U1 TPS61170DRV

0.22µF C15

2.2µF C13

2.2µF C4

4.7µF C14

R2 499k

R3 280k

R4 31.6k

L1 DR73-220-R

1µF C1

D1 MBRA141T3G

1000µF C5

1000µF C2

1000µF C6

1000µF C3

Capacitor Bank

Boost Enable(H)

PFET Enable(L)

Boost Enable(H)

PFET Enable(L)

150k R1

10K R12

Vbus (Boost Converter)
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